Dell EMC PowerEdge T550

Technical Specifications

Regulatory Model: E76S
Regulatory Type: E76S001
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Notes, cautions, and warnings

NOTE: A NOTE indicates important information that helps you make better use of your product.

CAUTION: A CAUTION indicates either potential damage to hardware or loss of data and tells you how to avoid the problem.

WARNING: A WARNING indicates a potential for property damage, personal injury, or death.

Contents

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Technical specifications

The technical and environmental specifications of your system are outlined in this section.

Topics:

Chassis dimensions

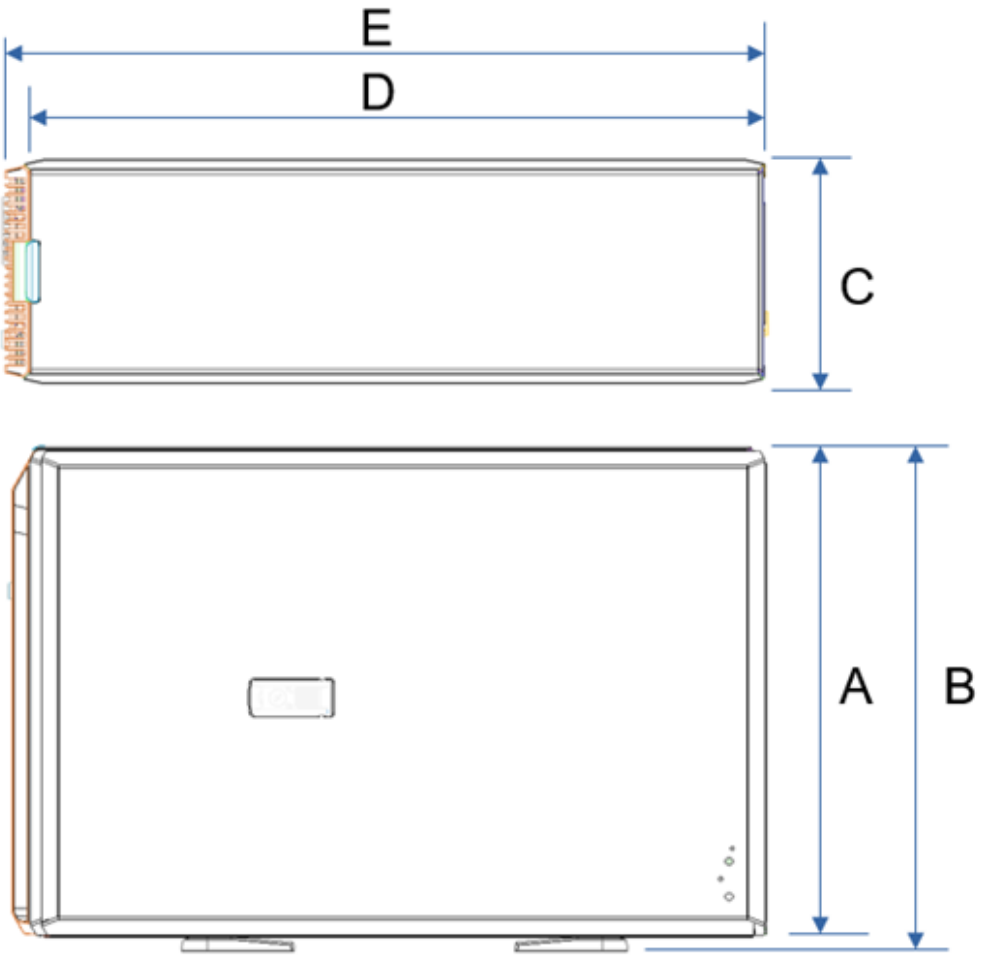

Figure 1. Chassis dimensions

Table 1. Chassis dimension for the system

Drives	A	B	C	D	E (with Bezel)
24 x 2.5-inch / 8 x 3.5-inch + 8 x 2.5-inch NVMe	446.0 mm (17.60 inches)	459.0 mm (18.07 inches)	200.0 mm (7.87 inches)	663.5 mm (26.12 inches)	680.5 mm (26.79 inches)

NOTE: Zb is the nominal rear wall external surface where the system board I/O connectors reside.

System weight

Table 2. System weight of the PowerEdge T550 system

System configuration	Maximum weight (with all drives/SSDs)
8 x 3.5-inch + 8 x 2.5-inch NVMe	44.48 kg (98.06 pound)
24 x 2.5-inch SAS/SATA	44.1 kg (97.22 pound)

Processor specifications

Table 3. Processor specifications for the system

Supported processor	Number of processors supported
3rd Generation Intel Xeon Scalable processors with up to 32 cores	Up to two

PSU specifications

The PowerEdge T550 system supports up to two AC power supply units (PSUs).

Table 4. PSU specifications

PSU	Class	Heat dissipation (maximum)	Frequency	Voltage	AC		DC	Current
					High line 200–240 V	Low line 100–120 V		
600 W Mixed Mode	Platinum	2250 BTU/hr	50/60 Hz	100 - 240 V, autoranging	600 W	600 W	N/A	7.1 A - 3.6 A
	N/A	2250 BTU/hr	N/A	240 V DC, autoranging	N/A	N/A	600 W	2.9 A
800 W Mixed Mode	Platinum	3000 BTU/hr	50/60 Hz	100 - 240 V, autoranging	800 W	800 W	N/A	9.2 A - 4.7 A
	N/A	3000 BTU/hr	N/A	240 V DC, autoranging	N/A	N/A	800 W	3.8 A
1100 W DC	N/A	4265 BTU/hr	N/A	-48 VDC – -60 VDC	N/A	N/A	1100 W DC	27 A
1100 W Mixed Mode	Titanium	4100 BTU/hr	50/60 Hz	100 - 240 V, autoranging	1100 W	1050 W	N/A	12 A - 6.3 A
	N/A	4100 BTU/hr	N/A	240 V DC, autoranging	N/A	N/A	1100 W DC	5.2 A
1400 W Mixed Mode	Platinum	5250 BTU/hr	50/60 Hz	100 - 240 V, autoranging	1400 W	1050 W	N/A	12 A - 8 A
	N/A	5250 BTU/hr	N/A	240 V DC, autoranging	N/A	N/A	1400 W	6.6 A
2400 W Mixed Mode	Platinum	9000 BTU/hr	50/60 Hz	100 - 240 V, autoranging	2400 W	1400 W	N/A	16 A - 13.5 A
	N/A	9000 BTU/hr	N/A	240 V DC, autoranging	N/A	N/A	2400 W	11.2 A

NOTE: This system is also designed to connect to the IT power systems with a phase-to-phase voltage not exceeding 240 V.

NOTE: Heat dissipation is calculated using the PSU wattage rating.

NOTE: When selecting or upgrading the system configuration, to ensure optimum power utilization, verify the system power consumption with the Enterprise Infrastructure Planning Tool available at Dell.com/calc.

Cooling fan specifications

The PowerEdge T550 system supports up to eight standard or high performance silver grade (HPR (Silver)) cooling fans connected to the system board directly.

Table 5. Cooling fan specifications

Fan type	Abbreviation	Also known as	Label color	Label image
High-performance fan (Silver grade) fan	HPR (Silver)	HPR - High Performance	N/A	 **Figure 2. High performance fan**
Standard fan	STD	STD - Standard	N/A	 **Figure 3. Standard fan**

NOTE: For more information about the supported fan configuration or matrix, see Thermal restriction matrix.

Supported operating systems

The PowerEdge T550 system supports the following operating systems:

- Canonical Ubuntu Server LTS
- Citrix Hypervisor
- Microsoft Windows Server with Hyper-V
- Red Hat Enterprise Linux
- SUSE Linux Enterprise Server
- VMware ESXi

For more information, go to www.dell.com/ossupport.

System battery specifications

The PowerEdge T550 system supports CR 2032 3.0-V lithium coin cell system battery.

Expansion card riser specifications

The system supports up to six PCI express (PCIe) Gen 4 expansion cards.

Table 6. Expansion card slots support matrix

PCIe slot	Processor 1	Platform Controller Hub (PCH)	Processor 2
	Internal	Internal	Internal
Slot 1	x16	-	-
Slot 2	-	-	x16
Slot 3	-	-	x16
Slot 4	-	-	x16
Slot 5	-	x8	-
Slot 6	x16	-	-

Table 7. Expansion card slots supported for Riser Configurations

PCIe slot	Riser configuration	Riser width	PERC supported	Rear storage supported
Slot 1	GPU riser	x16 PCIe	No	No
Slot 2	GPU riser	x16 PCIe	No	No

Memory specifications

The system supports the following memory specifications for optimized operation.

Table 8. Memory specifications

DIMM type	DIMM rank	DIMM capacity		DIMM Rated Voltage and supported speed	Speed	
		Single Processor	Dual Processor		Single Processor	Dual Processor
RDIMM	Single rank	8 GB	16 GB	DDR4 (1.2 V), 3200	3200	2933
		16 GB	32 GB	DDR4 (1.2 V), 3200	3200	2933
	Dual rank	16 GB	32 GB	DDR4 (1.2 V), 3200	3200	2933
		32 GB	64 GB	DDR4 (1.2 V), 3200	3200	2933

Table 9. Memory module sockets

Memory module sockets	Speed
16, 288-pin	3200 MT/s, 2933 MT/s,

Storage controller specifications

The PowerEdge T550 system supports the following controller cards:

Table 10. Storage controller cards

Internal controllers	External controllers
• S150 • PERC H345 • H355 • PERC H755 • H755N • HBA355i • Boot Optimized Storage Subsystem (BOSS-S2): HWRAID 2 x M.2 SSDs	• HBA355e • PERC H840

Drive specifications

Drives

The PowerEdge T550 system supports:

- Up to 8 x 2.5-inch SAS/SATA/ (HDD) drives
- Up to 16 x 2.5-inch SAS/SATA (HDD) drives
- Up to 24 x 2.5-inch SAS/SATA/ (HDD) drives
- Up to 8 x 3.5-inch SAS/SATA/ (HDD/SSD) drives
- Up to 8 x 3.5-inch SAS/SATA + 8 x 2.5-inch NVMe (HDD/SSD) drives

NOTE: For more information about how to hot swap NVMe PCIe SSD U.2 device, see the *Dell Express Flash NVMe PCIe SSD User's Guide* at https://www.dell.com/support **Browse all Products** > **Data Center Infrastructure** > **Storage Adapters & Controllers** > **Dell PowerEdge Express Flash NVMe PCIe SSD** > **Documentation** > **Manuals and Documents**.

Optical drives

The PowerEdge T550 system supports one Slim SATA DVD-ROM drive.

NOTE: DVD devices support only data.

Ports and connectors specifications

USB ports specifications

Table 11. USB specifications

Front		Rear	
USB port type	**No. of ports**	**USB port type**	**No. of ports**
USB 2.0-compliant port	One	USB 3.0-compliant port	One
USB 3.0-compliant port	One	USB 2.0-compliant port	One
iDRAC Direct port (Micro-AB USB 2.0-compliant port)	One		

NOTE: The front micro USB 2.0 compliant port is only available for the upsell configuration.

NOTE: The micro USB 2.0 compliant port can only be used as an iDRAC Direct or a management port.

NOTE: The USB 2.0 specifications provide a 5 V supply on a single wire to power connected USB devices. A unit load is defined as 100 mA in USB 2.0, and 150 mA in USB 3.0. A device may draw a maximum of 5 unit loads (500 mA) from a port in USB 2.0; 6 (900 mA) in USB 3.0.

NOTE: The USB 2.0 interface can provide power to low-power peripherals but must adhere to USB specification. An external power source is required for higher-power peripherals to function, such as external CD/DVD Drives.

NIC port specifications

The system supports up to two 10/100/1000 Mbps Network Interface Controller (NIC) ports embedded on the LAN on Motherboard (LOM) and integrated on the optional OCP cards.

Table 12. NIC port specification for the system

Feature	Specifications
LOM card	1 GB x 2
OCP card (OCP 3.0)	1 GbE x 4, 10 GbE x 2, 25 GbE x 2, 25 GbE x 4, 50 GbE x 2, 100 GbE x 2

VGA ports specifications

The system supports One DB-15 VGA port one each on the front and back panels.

Serial connector specifications

The PowerEdge T550 system supports one optional card type serial connector, which is a 9-pin connector, Data Terminal Equipment (DTE), 16550-compliant .

The optional serial connector card is installed similar to an expansion card filler bracket.

Video specifications

The system supports integrated Matrox G200 graphics controller with 16 MB of video frame buffer.

Table 13. Supported rear video resolution options for the system

Resolution	Refresh rate (Hz)	Color depth (bits)
1024 x 768	60	8, 16, 32
1280 x 800	60	8, 16, 32
1280 x 1024	60	8, 16, 32
1360 x 768	60	8, 16, 32
1440 x 900	60	8, 16, 32
1600 x 900	60	8, 16, 32
1600 x 1200	60	8, 16, 32
1680 x 1050	60	8, 16, 32
1920 x 1080	60	8, 16, 32
1920 x 1200	60	8, 16, 32

Environmental specifications

NOTE: For additional information about environmental certifications, refer to the Product Environmental Datasheet located with the Manuals & Documents on www.dell.com/support/home.

Table 14. Operational climatic range category A2

Temperature	Specifications
Allowable continuous operations	
Temperature ranges for altitudes <= 900 m (<= 2953 ft)	10–35°C (50–95°F) with no direct sunlight on the equipment
Humidity percent ranges (non-condensing at all times)	8% RH with -12°C minimum dew point to 80% RH with 21°C (69.8°F) maximum dew point
Operational altitude de-rating	Maximum temperature is reduced by 1°C/300 m (33.8°F/984 Ft) above 900 m (2953 Ft)

Table 15. Operational climatic range category A3

Temperature	Specifications
Allowable continuous operations	
Temperature ranges for altitudes <= 900 m (<= 2953 ft)	5–40°C (41–104°F) with no direct sunlight on the equipment
Humidity percent ranges (non-condensing at all times)	8% RH with -12°C minimum dew point to 80% RH with 24°C (75.2°F) maximum dew point
Operational altitude de-rating	Maximum temperature is reduced by 1°C/175 m (1.8°F/574 Ft) above 900 m (2953 Ft)

Table 16. Operational climatic range category A4

Temperature	Specifications
Allowable continuous operations	
Temperature ranges for altitudes <= 900 m (<= 2953 ft)	5–45°C (41–113°F) with no direct sunlight on the equipment
Humidity percent ranges (non-condensing at all times)	8% RH with -12°C minimum dew point to 80% RH with 24°C (75.2°F) maximum dew point
Operational altitude de-rating	Maximum temperature is reduced by 1°C/125 m (1.8°F/410 Ft) above 900 m (2953 Ft)

NOTE: Certain system hardware configurations may require operating temperatures to be less than 28°C. For more information, see the Thermal air restrictions section.

Table 17. Shared requirements across all categories

Temperature	Specifications
Allowable continuous operations	
Maximum temperature gradient (applies to both operation and non-operation)	20°C in an hour* (36°F in an hour) and 5°C in 15 minutes (41°F in 15 minutes), 5°C in an hour* (41°F in an hour) for tape **NOTE:** * - Per ASHRAE thermal guidelines for tape hardware, these are not instantaneous rates of temperature change.
Non-operational temperature limits	-40 to 65°C (-104 to 149°F)
Non-operational humidity limits	5% to 95% RH with 27°C (80.6°F) maximum dew point
Maximum non-operational altitude	12,000 meters (39,370 feet)

Table 17. Shared requirements across all categories (continued)

Temperature	Specifications
Maximum operational altitude	3,048 meters (10,000 feet)

Table 18. Maximum vibration specifications

Maximum vibration	Specifications
Operating	0.21 G_{rms} at 5 Hz to 500 Hz (all operation orientations)
Storage	1.88 G_{rms} at 10 Hz to 500 Hz for 15 minutes (all six sides tested)

Table 19. Maximum shock pulse specifications

Maximum shock pulse	Specifications
Operating	Six consecutively executed shock pulses in the positive and negative x, y, and z axis of 6 G for up to 11 ms.
Storage	Six consecutively executed shock pulses in the positive and negative x, y, and z axis (one pulse on each side of the system) of 71 G for up to 2 ms.

Thermal restriction matrix

Table 20. Thermal restriction matrix

Drive Configuration	Processor	Fans	CPU TDP	Fan redundancy	CPU HSK		GPU support		TBU support	CPU blank	Fan blank	Note	GPU riser configuration
					TDP>150 W	TDP<=150 W	GPU<=75 W	GPU>75 W					
8 x 3.5	1	STD x3	<=185	No	HPR HSK	STD HSK	No	No	No	Yes	Yes at Fan 2 location	Fan 1/3/4	Riser 0, 1
	1	STD x6	<=220	Yes			No	No	No	Yes		Fan 1/3/4/5/7/8	Riser 0, 1
	1	HPR x3	<=220	No			Yes	No	No	Yes		Fan 1/3/4	No
	1	HPR x5*	<=220	Yes			Yes/No	No	Yes	Yes		Fan 1/3/4/7/8 (GPU riser 1 and 2 not supported)	No
	1	HPR x6	<=220	Yes			Yes	Yes	No	Yes		Fan 1/3/4/5/7/8	Yes
	2	STD x4	<=185	No			No	No	No	No	No	NA	Riser 0, 1
	2	STD x8	<=220	Yes			No	No	No	No		NA	Riser 0, 1
	2	HPR x4	<=220	No			Yes	No	No	No		NA	No
	2	HPR x7*	<=220	Yes			Yes/No	No	Yes	No		Fan 1/2/3/4/6/7/8 **NOTE:** GPU riser 1 and 2 not supported	No
	2	HPR x8	<=220	Yes			Yes	Yes	No	No		NA	Yes
8 x 2.5 16 x 2.5 24 x 2.5	1 or 2	STD x4	<=185	No	HPR HSK	STD HSK	No	No	No	Yes for 1 processor	No	NA	Riser 0, 1
	1 or 2	STD x8	<=220	Yes			No	No	No			NA	Riser 0, 1
	1 or 2	HPR x4	<=220	No			Yes	No	No			NA	No
	1 or 2	HPR x7*	<=220	Yes			Yes/No	No	Yes			Fan 1/2/3/4/6/7/8	No

Table 20. Thermal restriction matrix (continued)

Drive Configuration	Processor	Fans	CPU TDP	Fan redundancy	CPU HSK		GPU support		TBU support	CPU blank	Fan blank	Note	GPU riser configuration
					TDP>150 W	TDP<=150 W	GPU<=75 W	GPU>75 W					
												NOTE: GPU riser 1 and 2 not supported	
	1 or 2	HPR x8	<=220	Yes			Yes	Yes	No			NA	Yes
8 x 3.5 + 8 x 2.5 (NVMe)	1 or 2	HPR x4	<=220	No	HPR HSK	STD HSK	Yes	No	No	Yes for 1 processor	No	NA	No or Riser 0, 1, 2
	1 or 2	HPR x7*	<=220	Yes			Yes/No	No	Yes			Fan 1/2/3/4/6/7/8 NOTE: GPU riser 1 and 2 not supported	No
	1 or 2	HPR x8	<=220	Yes			Yes	Yes	No			NA	Yes

NOTE: OCP shroud are required for all drive configurations, even if the OCP card is not installed.

NOTE: DIMM blanks are required for CPU TDP>185 W, but are not required for CPU TDP<=185 W.

NOTE: GPU blank is required at GPU riser slot 2, when a GPU>75 W is installed at GPU riser slot 1.

NOTE: HDD blanks are required for empty HDD slots.

NOTE: *x5 and x7 fan count is applicable only for TBU configuration. Systems without TBU should not use x5 and x7 fan counts. For TBU configuration, ambient temperature is < 35C.

NOTE: When GPU is selected, HPR fan must be required.

NOTE: GPU>75W must require fan redundancy (Fan quantity = 6 or 8).

NOTE: GPU>75 W does not support TBU.

NOTE: STD fans can also be upgraded to HPR fans.

Thermal matrix for all configurations

Table 21. Thermal matrix for all configurations

-		8x, 16x, 24x 2.5-inch SAS/SATA Configuration 1				8x 3.5-inch Configuration 2				8x 3.5-inch + 8x 2.5-inch NVMe Configuration 3	
Fan		STDx4	STDx8	HPRx4	HPRx7 x8	STDx3 x4	STDx6 x8	HPRx3 x4	HPRx5 x6 x7 x8	HPRx4	HPRx7 x8
Fan redundancy		No	Yes	No	Yes	No	Yes	No	Yes	No	Yes
Maximum DIMM power		12 W	12 W	12 W	12 W	12 W	12 W	12 W	12 W	12 W	12 W
CPU TDP	105 W	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK
	120 W	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK
	125 W	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK
	135 W	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK
	150 W	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK
	165 W	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK
	185 W	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK
	205 W	Not supported	HPR HSK	HPR HSK	HPR HSK	Not supported	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK
	220 W	Not supported	HPR HSK	HPR HSK	HPR HSK	Not supported	HPR HSK	HPR HSK	HPR HSK	HPR HSK	HPR HSK

Particulate and gaseous contamination specifications

The following table defines the limitations that help avoid any damages to the IT equipment and/or, or both failure from particulate and gaseous contamination. If the levels of particulate or gaseous pollution exceed the specified limitations and results in equipment damage or failure, you must rectify the environmental conditions. Remediation of environmental conditions is the responsibility of the customer.

Table 22. Particulate contamination specifications

Particulate contamination	Specifications
Air filtration	Data center air filtration as defined by ISO Class 8 per ISO 14644-1 with a 95% upper confidence limit. **NOTE:** This condition applies to data center environments only. Air filtration requirements do not apply to IT equipment designed to be used outside a data center, in environments such as an office or factory floor. **NOTE:** Air entering the data center must have MERV11 or MERV13 filtration.
Conductive dust	Air must be free of conductive dust, zinc whiskers, or other conductive particles. **NOTE:** This condition applies to data center and non-data center environments.
Corrosive dust	• Air must be free of corrosive dust. • Residual dust present in the air must have a deliquescent point less than 60% relative humidity. **NOTE:** This condition applies to data center and non-data center environments.

Table 23. Gaseous contamination specifications

Gaseous contamination	Specifications
Copper Coupon Corrosion rate	<300 Å/month per Class G1 as defined by ANSI/ISA71.04-2013
Silver Coupon Corrosion rate	<200 Å/month as defined by ANSI/ISA71.04-2013

NOTE: Maximum corrosive contaminant levels measured at ≤50% relative humidity.

Thermal air restrictions

Thermal air restrictions for different configurations

Table 24. 8 x 3.5-inch drive configuration

Standard Operating Support (ASHRAE A2 compliant) **NOTE:** All options supported unless otherwise noted.	Extended ambient 40° C Operating Support (ASHRAE A3 compliant)	Extended ambient 45° C Operating Support (ASHRAE A4 compliant)
• 3x or 4x STD fans support only processor with TDP<=185W • With STD fans, the following OCP 3.0 and NIC support only optic cable with thermal spec 85C and power <=1.2 W	• 3x or 4x STD fans configurations not supported. • 6x or 8x STD fans configurations with processor TDP > 120 W is not supported. • TBU not supported.	• STD fans configurations are not supported. • 3x or 4x HPR fans configurations with CPU TDP > 165 W are not supported. • TBU not supported.

Table 24. 8 x 3.5-inch drive configuration

Standard Operating Support (ASHRAE A2 compliant) **NOTE:** All options supported unless otherwise noted.	Extended ambient 40° C Operating Support (ASHRAE A3 compliant)	Extended ambient 45° C Operating Support (ASHRAE A4 compliant)
○ Broadcom OCP 3.0 QP 25G SFP28 ○ Broadcom PCIe QP 25G ○ NVIDIA CX6-LX PCIe Dual Port 25G SFP28 at slot 6	• Non-Dell qualified peripheral cards and Channel devices (FW) cards not supported. • NIC consuming power >= 25 W not supported. For example: CX6 card. • OCP transfer rate > 25G or cooling tier>10 is not supported. • Optic cable with spec 85C is required. • Two PSUs are required. System performance may be reduced in the event of a PSU failure.	• BOSS M.2 module not supported. • Non-Dell qualified peripheral cards and Channel devices (FW) cards are not supported. • NIC consuming power >= 25 W. For example: CX6 card. • OCP transfer rate >25G or cooling tier > 10 not supported. • Optic cable with spec 85C is required. • Two PSUs are required. System performance may be reduced in the event of a PSU failure.

Table 25. 8 x 2.5-inch, 16 x 2.5-inch, 24 x 2.5-inch drive configuration

Standard Operating Support (ASHRAE A2 compliant)	Extended ambient 40° C Operating Support (ASHRAE A3 compliant)	Extended ambient 45° C Operating Support (ASHRAE A4 compliant)
• 4x STD fans support only processor with TDP<=185W • With STD fans, the following OCP 3.0 and NIC support only optic cable with thermal Spec 85C and power <=1.2 W ○ Broadcom OCP 3.0 QP 25G SFP28 ○ Broadcom PCIe QP 25G ○ NVIDIA CX6-LX PCIe Dual Port 25G SFP28 at slot 6	• 4x STD fans configurations not supported. • 8x STD fans configurations with CPU TDP > 120 W is not supported. • TBU not supported. • Non-Dell qualified peripheral cards and Channel devices (FW) cards are not supported. • NIC consuming power >= 25 W not supported. For example: CX6 card. • OCP transfer rate > 25G or cooling tier > 10 not supported. • Optic cable with spec 85C is required. • Two PSUs are required. System performance may be reduced in the event of a PSU failure.	• STD fans configurations are not supported. • 4x HPR fans configurations with processor TDP > 165 W are not supported. • TBU not supported. • BOSS M.2 module is not supported. • Non-Dell qualified peripheral cards and Channel devices (FW) cards are not supported. • NIC consuming power >= 25 W. For example: CX6 card. • OCP transfer rate >25G or cooling tier > 10 not supported. • Optic cable with spec 85C is required. • Two PSUs are required. System performance may be reduced in the event of a PSU failure.

Table 26. 8 x 3.5-inch x 8 x NVMe drive configuration

Standard Operating Support (ASHRAE A2 compliant)	Extended ambient 40° C Operating Support (ASHRAE A3 compliant)	Extended ambient 45° C Operating Support (ASHRAE A4 compliant)
HPR fans are required.	• TBU not supported. • Non-Dell qualified peripheral cards and Channel devices (FW) cards are not supported. • NIC consuming power >= 25 W not supported. For example: CX6 card. • OCP transfer rate > 25G or cooling tier > 10 not supported. • Optic cable with spec 85C is required.	• 4x HPR fans configurations with CPU TDP > 165 W are not supported. • TBU not supported. • BOSS M.2 module is not supported. • Non-Dell qualified peripheral cards and Channel devices (FW) cards are not supported. • NIC consuming power >= 25 W. For example: CX6 card. • OCP transfer rate >25G or cooling tier > 10 not supported.

Table 26. 8 x 3.5-inch x 8 x NVMe drive configuration

Standard Operating Support (ASHRAE A2 compliant)	Extended ambient 40° C Operating Support (ASHRAE A3 compliant)	Extended ambient 45° C Operating Support (ASHRAE A4 compliant)
	• Two PSUs are required. System performance may be reduced in the event of a PSU failure.	• Optic cable with spec 85C is required. • Two PSUs are required. System performance may be reduced in the event of a PSU failure.